

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number						
		IP4220CZ6						
		Part Description						
		Nexperia DHAM	Protection Bipo	olar				
Assembly reliability labs		SMD package						
Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# 2	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	286	21480	0		
# 5	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	23	1840	0		
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	86	6880	0		
# 8	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	86	6880	0		
# 9	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$	1000 hours	86	6880	0		
# 10	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj = 100$ °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
# 20	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	28	840	0		
# 21	SD Solderability	J-STD-002		36	360	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection Bipolar	1840	0	2.31	4.33E+08

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